### 3.0x2.0mm SURFACE MOUNT LED LAMP

Part Number: KA-3021CGSK

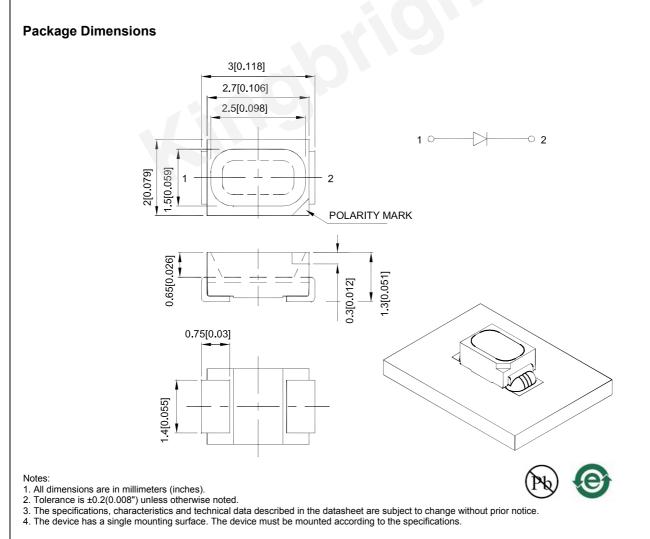
Green

### Features

- 3.0mm x 2.0mm, 1.3mm high, only minimum space required.
- Suitable for compact optoelectronic applications.
- Low power consumption.
- Package : 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

### Description

The Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.



SPEC NO: DSAL1421

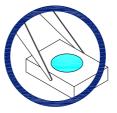
**APPROVED: Wynec** 

**REV NO: V.6B CHECKED: Allen Liu**  DATE: MAY/17/2016 DRAWN: W.Q.Zhong PAGE: 1 OF 6 ERP: 1201006490

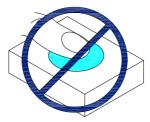
### **Handling Precautions**

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.



2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

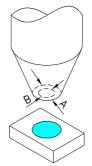




3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



5. As silicone encapsulation is permeable to gases, some corrosive substances such as  $H_2S$  might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

#### **Selection Guide** Viewing lv (mcd) [2] @ 20mA Angle [1] Part No. **Emitting Color (Material)** Lens Type Min. 201/2 Тур. KA-3021CGSK Green (AlGaInP) Water Clear 40 80 120°

Notes:

1.  $\theta$ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity/ luminous Flux: +/-15%.

3. Luminous intensity value is traceable to CIE127-2007 standards.

### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Emitting Color	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	574		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Green	570		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Green	20		nm	I⊧=20mA
С	Capacitance	Green	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Green	2.1	2.5	V	I⊧=20mA
IR	Reverse Current	Green		10	uA	VR=5V

Notes:

1.Wavelength: +/-1nm.

2.Forward Voltage: +/-0.1V.
Wavelength value is traceable to CIE127-2007 standards.

4.Excess driving current and/or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

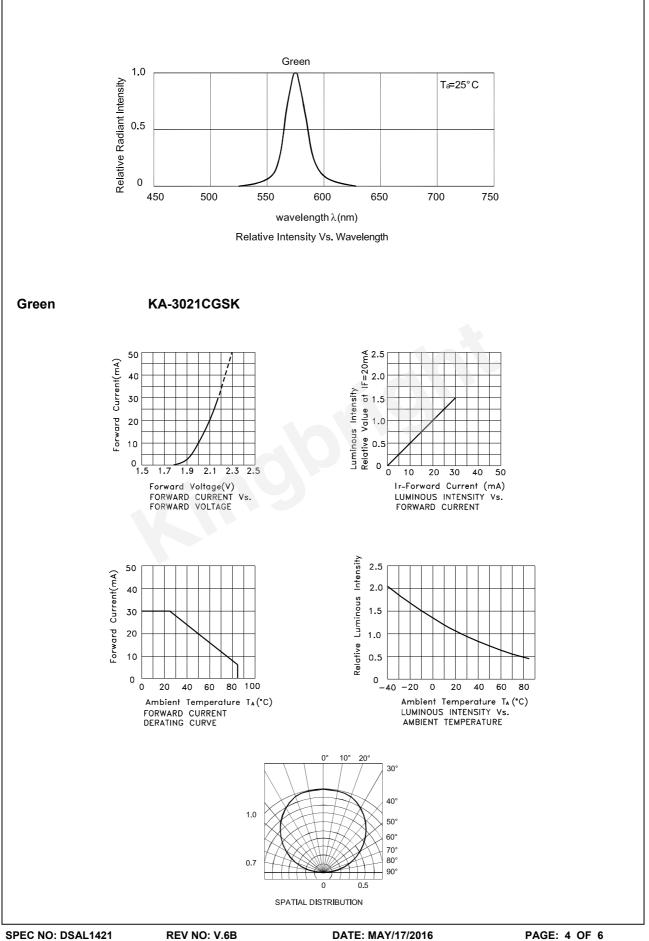
### Absolute Maximum Ratings at TA=25°C

Parameter	Values	Units		
Power dissipation	75	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	150	mA		
Reverse Voltage	5	V		
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +85°C			

Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

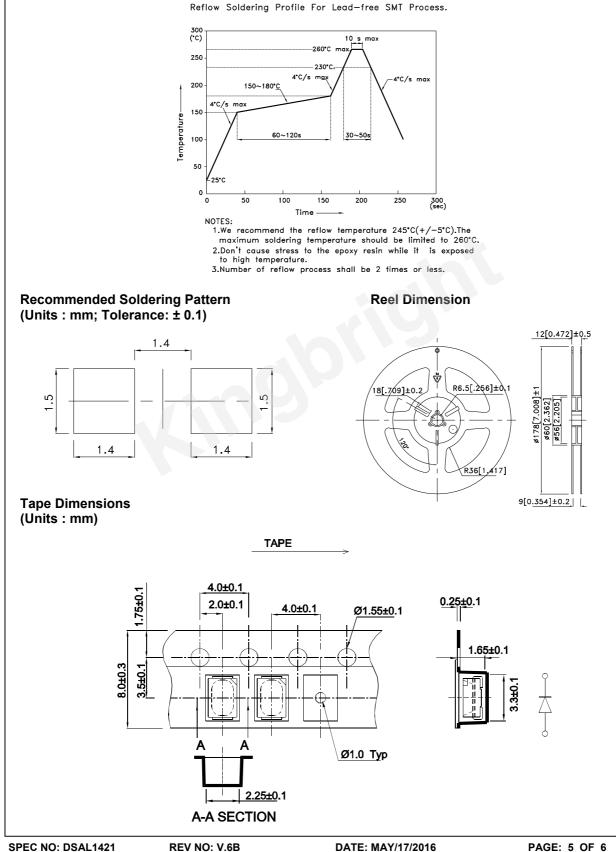
 Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.



## KA-3021CGSK

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



**APPROVED: Wynec** 

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